

Call for Papers

2017 FLEX Europe be flexible

15-16 November | Munich, Germany
Co-located with productronica

Invitation

End users, supply chain companies, R&D organizations, start-ups and universities are invited to submit abstracts for the 2017 FLEX Europe Conference. FLEX Europe Conference will be held in cooperation with Fraunhofer EMFT's forum BE-FLEXIBLE. This 2 day conference, an integral part of SEMICON Europa 2017 co-located with productronica, will address materials, manufacturing, new technologies and applications for flexible hybrid electronics (FHE) and printed electronics (PE) and will demonstrate the strong history of Europe in the field.

FLEX Europe 2017 Theme Description

By co-locating with Europe's largest semiconductor manufacturing event and held in cooperation with the Fraunhofer EMFT's forum BE-FLEXIBLE 2017, the FLEX Europe Conference takes advantage of the intersection of PE and thin silicon (Si) devices. Key technical topics are expected to be covered such as: Thin Silicon, Flexible Sensors, Heterointegration on Flex, Bendable Electronics, Reliability of Flexible Electronics, and Robotics. We can leverage the assets of the global semiconductor industry to build a new class of flexible hybrid electronics (FHE). Markets being impacted by FHE include structural health monitoring, the Internet of Things (IOT), and medical devices, among others. Specific applications include wearable electronics, smart packaging, smart sensor systems, and physiological monitoring devices.

FLEX Europe Conference 2017 – Recommended List of Topics for Presentations

Business Strategies & Market Overview

- Perspective for Flexible Electronics
- Technology Roadmap
- Hybrid-Electronics Approach
- Trends in Systems-in-Package (SiP)
- Funding Programs
- Gap Analysis
- Emerging Markets

Integration Processes on Flex

- Thin Silicon, Thin Wafer Handling
- Die Handling & Packaging
- Interconnect Technologies
- System Integration / Heterogeneous Integration
- Testing & Reliability

Material Advancements <ul style="list-style-type: none"> ▪ Substrates ▪ Conductors, Insulators, Semiconductors ▪ Functional Inks ▪ Fibers & Textiles ▪ Nanomaterials, 2D Materials, Graphene ▪ Bio-Compatible Materials ▪ Adhesives, Encapsulants 	Flex Components <ul style="list-style-type: none"> ▪ Sensors on Flex ▪ Flex Displays ▪ Energy Sources, Batteries ▪ Harvesters, PVs ▪ Membrane Switches ▪ Low Power Communication / Control Modules ▪ Circuit passives ▪ Antenna
Equipment & Tools <ul style="list-style-type: none"> ▪ Pick & Place ▪ Die Bonding ▪ Substrate Handling ▪ Roll-to-Roll Processing ▪ Metrology and Testing ▪ Scale-up for Production 	Applications <ul style="list-style-type: none"> ▪ Wearables, Stretchables, Smart Fashion ▪ Smart Healthcare, Assisted Living, Prosthetics ▪ Internet of Things Sensor Nodes ▪ Robotics, Electronic Skin ▪ Smart Buildings, Infrastructure Condition Monitoring ▪ Smart Packaging ▪ Automotive, Avionics, Transportation ▪ Smart Farming, agriculture

Instructions to submit an abstract

To submit your abstract please click [here](#).

General guidelines:

- Review the list of recommended topics on Page 1
- Please submit your abstracts, biography and a photo via internet until **12 May 2017**. Abstracts submitted via fax, e-mail, post, or other methods will generally not be accepted.
- The conference language is English.
- The abstract should have between 1.000 and 2.000 characters (Starting with descriptive paragraph identifying issue addressed and solution).
- Abstract changes and corrections will be accepted until the **12 May 2017**.

Your presentation may not be included in the review process unless the information is complete.

Evaluation criteria include significance, usefulness for the manufacturing world and clarity and accuracy as a paper. Abstracts will be peer-reviewed and selected relative to the points above. We encourage application related presentations, i.e., on joint projects between users and suppliers. Papers are to be non-commercial and focus on the technical/economical merits of a process rather than the individual company's product benefits.

Deadline: Submit your abstracts and biography until **12 May 2017**.

Changes: After your first registration your data are saved. Changes can be made any time until **12 May 2017**.

Notification: Selected presenters will be notified by **17 July 2017**.

With best regards from the Flex Europe Committee,

Committee members:

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| • Karl-Heinz Bock, Technische Universität Dresden | Michael Ciesinski, FlexTech Alliance |
| • Istvan Denes, Bosch | Jerome Gavillet, Cea-Leti |
| • Mike Hack, Universal Display Corp. (UDC) | Heidi Hoffman, SEMI |
| • Ryoichi Ishihara, TU Delft | Antti Kempainen, VTT |
| • Christoph Kutter, Fraunhofer EMFT (chairman) | Christof Landesberger, Fraunhofer EMFT |
| • Claus Lichtenberg, Roth & Rau BV | Luigi Occhipinti, Univ. of Cambridge |
| • Andreas Toennis, AIXTRON SE | |
| • Andre Zimmermann, Universität Stuttgart / Hahn-Schickard-Gesellschaft | |